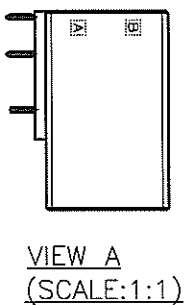
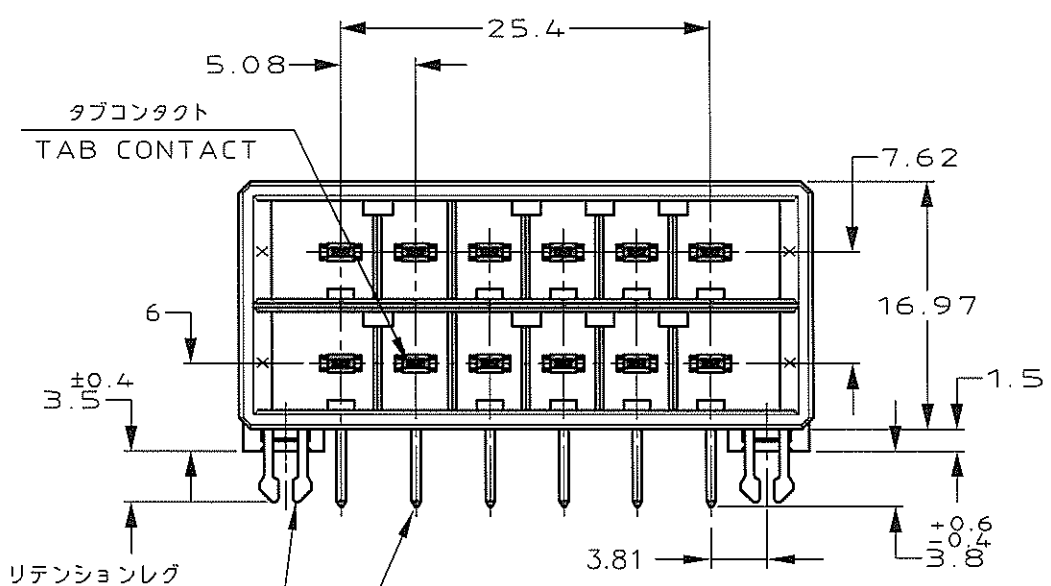
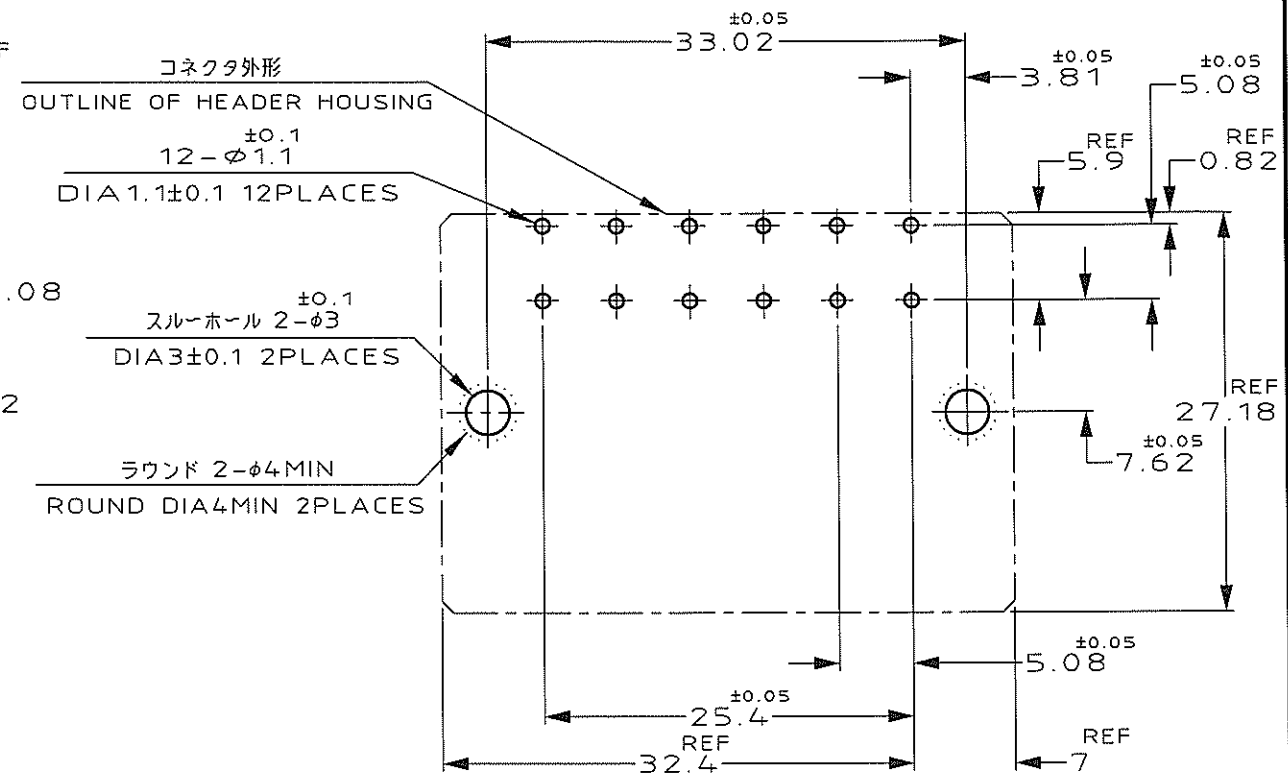
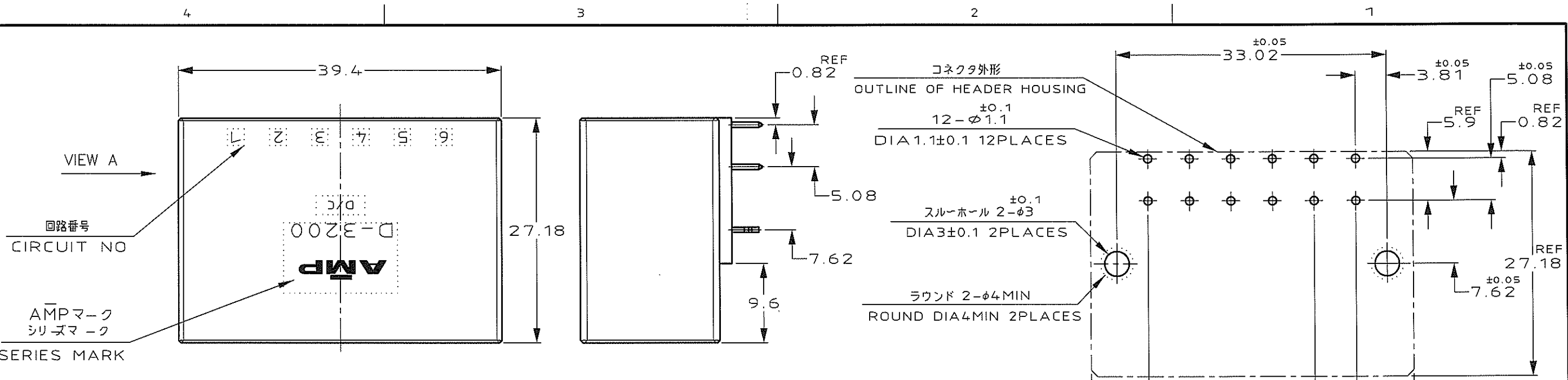


NUMBER 316081  
 METRIC  
 DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT  
 PRINT DIST



推奨基板取付け穴寸法  
 PC 基板厚: 1.6 ± 0.1  
 (非累積公差)  
 (コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
 PC BOARD THICKNESS: 1.6 ± 0.1  
 (NOT ACCUMULATE TOLERANCE)  
 (CONNECTOR MOUNT SIDE)

**NOTES**  
 1. MATERIAL: HOUSING: GLASS FIBER THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK  
 CONTACT: COPPER ALLOY  
 RETENTION LEG: COPPER ALLOY  
 2. FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING  
 3. FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING  
 4. FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL  
 5. FINISH (RETENTION LEG): TIN LEAD PLATED (CONTACT TAIL) OVER NICKEL  
 6. FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL  
 7. OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

**注記**  
 1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒  
 コネクタ: 銅合金  
 リテンションレグ: 銅合金  
 2. めっき: コネクタ: 全面Ni下地 接触部: 0.38 μm MIN金めっき  
 3. めっき: コネクタ: 全面Ni下地 接触部: 0.76 μm MIN金めっき  
 4. めっき: コネクタ: 全面Ni下地 接触部: 2.0 μm MINスズめっき  
 5. めっき: リテンションレグとコンタクト半田付部: ニッケル下地の上に半田めっき  
 6. めっき: リテンションレグとコンタクト半田付部: ニッケル下地の上にスズめっき

KEYING LOCATION	A ROW KEYING	B ROW KEYING	FINISH	製品番号	PART NO.
B ROW	X	Y	△6 △4	3-316081-5	△7
A ROW	X	Y	△6 △3	3-316081-3	
			△6 △2	3-316081-2	
B ROW	Y	Y	△6 △4	2-316081-5	
A ROW	Y	Y	△6 △3	2-316081-3	
			△6 △2	2-316081-2	
B ROW	X	X	△6 △4	1-316081-5	
A ROW	X	X	△6 △3	1-316081-3	
			△6 △2	1-316081-2	

WIRE RANGE		INSULATION DIA		NAME	
mm(AWG)		mm		12 POS DOUBLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC D-3200	
MATERIAL SEE NOTE 注記参照		FINISH SEE NOTE 注記参照		一般公差 (GENERAL TOLERANCE)	
DR. 4/JUL/95 K.IKEDA		DE. 4/JUL/95 K.IKEDA		SIZE	LOC
CHK. 4/JUL/95 Y.ISHIKAWA		APP. 4/JUL/95 S.MANABE		A3	J
				NUMBER	REV.
				C-316081	B4
				SCALE	SHEET
				2-1	1 OF 1

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